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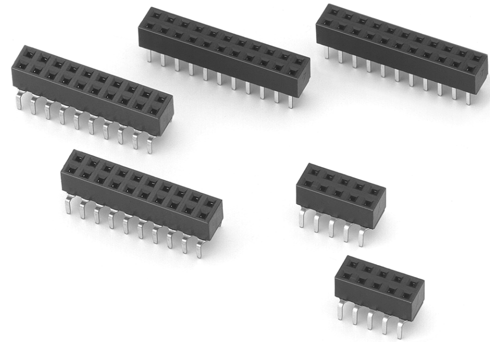
Buchsenleiste RM 2,54 mm - 2-reihig - durchsteckbar

Female Header - Double Row - Pitch 2,54 mm - Dual Entry

B

Technische Daten / *Technical Data*:

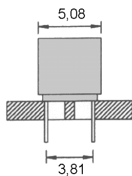
Isolierkörper	Thermoplastischer Kunststoff, nach UL94V0
Insulator	*Thermoplastic, rated UL94V0*
Kontaktmaterial	Kontakt für Vierkantstift □ 0,635 mm, CuZn 30
Contact Material	*Contact for Square Pin □ 0,635 mm, CuZn 30*
Kontaktoberfläche	lt. Oberflächenoptionen, über Ni (1,3-2,5 µm)
Contact Surface	*acc. to options (see below), over Ni (1,3-2,5 µm)*
Lötbarkeit	IEC512-12A
Solderability	*IEC512-12A*
Durchgangswiderstand	$\leq$ 20 mOhm
Contact Resistance	*$\leq$ 20 mOhm*
Isolationswiderstand	> 10^9 Ohm
Insulation Resistance	*> 10^9 Ohm*
Spannungsfestigkeit	1000 V_{DC}
Test Voltage	*1000 V_{DC}*
Nennspannung	250 V_{AC}
Current Voltage	*250 V_{AC}*
Nennstrom	3 A
Current Rating	*3 A*
Temperaturbereich	-40°C...+105°C
Temperature Range	*-40°C...+105°C*
Verarbeitung	Reflow-Lötverfahren; weitere Informationen in Kapitel T
Processing	*Reflow-Soldering, further informations in chapter T*

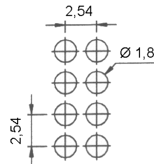


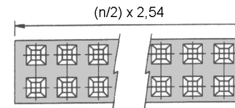
Doppelfederkontakt für Vierkantstift □ 0,635 mm

Dual beam contact accepts square pin □ 0,635 mm

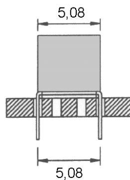
LAYOUT 1

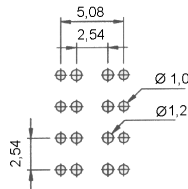


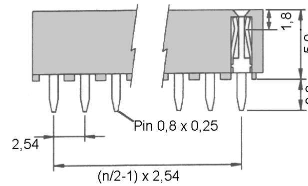




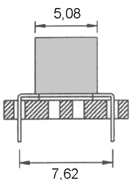
LAYOUT 2

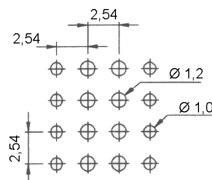






LAYOUT 3





04-80-pol. zweireihig
double row

1 = Raster 3,81 mm
Dip Spacing
2 = Raster 5,08 mm
Dip Spacing
3 = Raster 7,62 mm
Dip Spacing

00 = vergoldet
gold plated
50 = verzinnt
tin plated

(* Bestellbeispiel - Bitte durch Ihre Spezifikationen ersetzen.
** Order example - To be replaced by your specifications.*)

Reflow-Lötverfahren
Reflow-Soldering

Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflowverfahren verarbeitet werden (Maximalwerte):

Profil Eigenschaft	**Bleifreies Löten**
Durchschnitts-Ramp-Up Rate (Ts_{max} to Tp)	3 °C / Sek. Max.
Vorheizen - Temperatur Min (Ts_{min}) - Temperatur Max (Ts_{max}) - Zeit (ts_{min} auf ts_{max})	 150°C 200°C 60-180 Sekunden
Verbleiben oberhalb: - Temperatur (T_L) - Zeit (t_L)	 217°C 60-150 Sekunden
Peak/Klassifizierung Temperatur (Tp)	260°C +/- 5°C
Zeit innerhalb von 5°C um die Peak-Temperatur (tp)	20-40 Sekunden
Ramp-Down Rate	6°C / Sekunde max.
Zeit von 25°C bis zur Peak-Temperatur	8 Minuten max.

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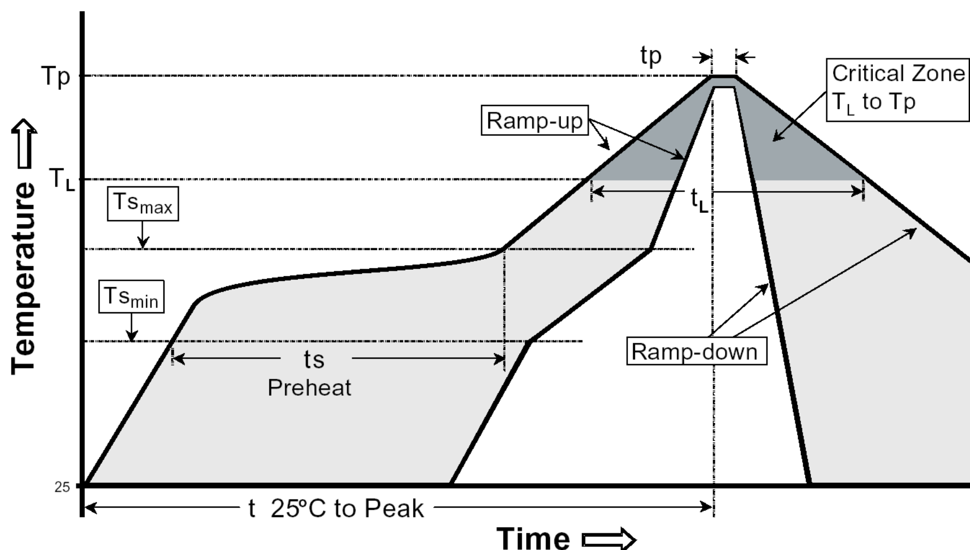
Items should be soldered according to IPC/JEDEC J-STD-020C temperature-profile for leadfree reflow-soldering (maximum values):

Profile Feature	**PB-Free assembly**
Average Ramp-Up Rate (Ts_{max} to Tp)	3 °C / second max.
Preheat - Temperature Min (Ts_{min}) - Temperature Max (Ts_{max}) - Time (ts_{min} to ts_{max})	 150°C 200°C 60-180 seconds
Time maintained above: - Temperature (T_L) - Time (t_L)	 217°C 60-150 seconds
Peak/Classification Temperature (Tp)	260°C +/- 5°C
Time within 5°C of actual Peak Temperature (tp)	20-40 seconds
Ramp-Down Rate	6°C / second max.
Time 25°C to Peak Temperature	8 minutes max.

Empfohlenes Reflow-Lötprofil:
Recommended Reflow-Soldering profile:



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